

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL14A105MP8NANC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1µF, 10V, ±20%, X5R, 0504

#### A. Samsung Part Number

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① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0504 (inch code)	L: 1.37 ± 0.15 mm	W: 1.0 ± 0.15 mm
③ Dielectric	X5R	8 Inner electrode	Ni
Capacitance	<b>1</b> μF	Termination	Cu
⑤ Capacitance	±20 %	Plating	Sn 100% (Pb Free)
tolerance		<b>9</b> Product	Array(2-element)
Rated Voltage	10 V	Special	Reserved for future use
① Thickness	0.8 ± 0.08 mm	① Packaging	Cardboard Type, 7" reel

#### B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms		
Tan δ (DF)	0.1 max.			
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.		
Resistance	Whichever is Smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	250% of the rated voltage		
Voltage	mechanical breakdown			
Temperature	X5R			
Characterisitcs	(From -55 ℃ to 85 ℃, Capacitance change shoud be within ±15%)			
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)		
		with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder		
	is to be soldered newly	235±5℃, 5±0.5sec.		
		2) SnAg3.0Cu0.5 solder		
		245±5℃, 3±0.3sec.		
		(preheating : 80~120℃ for 10~30sec.)		
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	Tan δ, IR : initial spec.			

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Humidity	Capacitance change : within ±12.5%	40±2℃, 90~95%RH, 500+12/-0hrs
	Tan δ : 0.125 max	
	IR: 25MΩ·μF or Over	
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 12.5MΩ·μF or Over	
High Temperature	Capacitance change : within ±12.5%	With 100% of the rated voltage
Resistance	Tan δ : 0.125 max	Max. operating temperature
	IR : 25MΩ·μF or Over	
		1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur→ 25 ℃
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}{ m C}$
		5 cycle test

### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.